

SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- A-Port Outputs Have Equivalent 50-Ω Series Resistors and B-Port Outputs Have Equivalent 20-Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Packaged in Thin Very Small-Outline Package

NOTE: For order entry, the DBB package is abbreviated to G. For tape and reel, the DBBR package is abbreviated to GR.

DESCRIPTION

The SN74ALVCHG162282 is an 18-bit to 36-bit registered bus exchanger. This device is intended for use in applications where data must be transferred from a narrow high-speed bus to a wide lower-frequency bus. It is designed specifically for low-voltage (3.3-V) V_{CC} operation.

The device provides synchronous data exchange between the two ports. Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input. For data transfer in the B-to-A direction, the select (SEL) input selects 1B or 2B data for the A outputs.

For data transfer in the A-to-B direction, a two-stage pipeline is provided in the 1B path, with a single storage register in the 2B path. Data flow is controlled by the active-low output-enable (\overline{OE}) and direction-control (DIR) input. DIR is registered to synchronize the bus direction changes with the clock.

DBB PACKAGE (TOP VIEW)						
		10		_ ,	1	
V _{CC}	Ч	1	U	80	h	V _{CC}
GND	Ы	2		79	Б	GND
2B9	Ы	3		78	Б	1B10
1B9	Ы	4		77	Б	2B10
2B8	Ы	5		76	Б	1B11
GND	Ы	6		75	Б	GND
1B8	Ы	7		74	Б	2B11
2B7	Н	8		73	К	1B12
2B7 1B7	Н	9		72	К	2B12
	Н	10		71	К	
V _{CC} 2B6	Н	11		70	Б	V _{CC} 1B13
2B0 1B6	Н	12		69	К	2B13
2B5	Н	13		68	К	
-	Н	14		67	К	1B14
1B5	Н	14		66	К	2B14
GND	Н	16		65	К	GND
2B4	Н	17		64	К	1B15
1B4	Н				K	2B15
2B3	Н	18		63	K	1B16
1B3	Н	19		62	K	2B16
V _{CC}	Н	20		61 60	K	V _{CC}
GND	Н	21		60	K	GND
2B2	Н	22		59	K	1B17
1B2	Н	23		58	K	2B17
2B1	Н	24		57	Ľ	1B18
1B1	Н	25		56	R	2B18
V _{CC}	Ч	26		55	ĥ	V _{CC}
A1	Ч	27		54	ĥ	A18
A2	Ч	28		53	ĥ	A17
A3	Ч	29		52	ĥ	A16
GND	Ч	30		51	ĥ	GND
A4	Ч	31		50	ĥ	A15
A5	Ч	32		49	Ľ	A14
A6	Ц	33		48	ĥ	A13
V _{CC}	Ц	34		47	Ц	V _{CC}
A7	Ц	35		46	ĥ	A12
A8	Ц	36		45	Ŕ	A11
A9	Ц	37		44	ĥ	A10
GND	Ц	38		43	ĥ	GND
CLK	Ц	39		42	ĥ	OE
SEL	Ц	40		41	μ	DIR



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SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004

DESCRIPTION (CONTINUED)

The A-port N-channel output transistors are sized at 450 μ m, and the P-channel output transistors are sized at 700 μ m. All A-port outputs have equivalent 50- Ω series resistors. The B-port N-channel output transistors are sized at 225 μ m, and the P-channel output transistors are sized at 560 μ m. All B-port outputs have equivalent 20- Ω series resistors

IEXAS

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Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The switching characteristics are based on 25-pF (A port) and 80-pF (B port) loads, but are tested with the standard 50-pF load.

The SN74ALVCHG162282 is characterized for operation from 0°C to 70°C.

FUNCTION TABLES

A-TO-B STORAGE (OE = L, DIR = H)

	INPUTS		OUT	PUTS
SEL	CLK	Α	1B	2B
Н	Х	Х	1B ₀ ⁽¹⁾	2B ₀ ⁽¹⁾
L	\uparrow	L	L ⁽²⁾	L
L	\uparrow	Н	H ⁽²⁾	Н

(1) Output level before indicated steady-state input conditions were established

(2) Two CLK edges are needed to propagate the data.

B-TO-A STORAGE (OE = L, DIR = L)

	INP	UTS		OUTPUT
CLK	SEL	1B	2B	Α
\uparrow	Н	Х	L	L ⁽¹⁾
\uparrow	Н	Х	Н	H ⁽¹⁾
\uparrow	L	L	Х	L
\uparrow	L	Н	Х	н

(1) Two CLK edges are needed to propagate the data. The data is loaded in the first register when SEL is low and propagates to the second register when SEL is high.

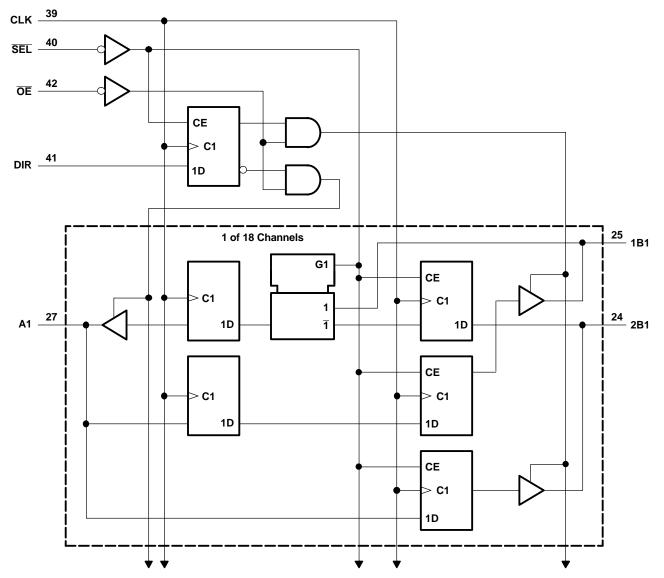
OUTPUT ENABLE

	INPUTS		OUT	PUTS
CLK	OE	DIR	Α	1B, 2B
↑	Н	Х	Z	Z
↑	L	Н	Z	Active
\uparrow	L	L	Active	Z



SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004





SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
		Except I/O ports ⁽²⁾	-0.5	V _{CC} + 0.5	V
VI	Input voltage range	I/O ports ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	v
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾			106	°C/W
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The input and output positive voltage ratings may be exceeded up to 4.6 V if the input and output clamp-current ratings are observed.

(4) The package thermal impedance is calculated in accordance with JESD 51.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

				MIN	MAX	UNIT
V_{CC}	Supply voltage			3	3.6	V
VIH	High-level input voltage		V_{CC} = 3 V to 3.6 V	2		V
V_{IL}	Low-level input voltage		V_{CC} = 3 V to 3.6 V		0.8	V
VI	Input voltage				V _{CC}	V
Vo	Output voltage				V _{CC}	V
	Llich lovel output ourrent	A to B	$V_{CC} = 3 V$		8	~^^
I _{OH}	High-level output current	B to A	$V_{CC} = 3 V$		6	mA
		A to B	$V_{CC} = 3 V$		8	~^^
I _{OL}	Low-level output current	B to A	$V_{CC} = 3 V$		6	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		·		10	ns/V
T _A	Operating free-air temperature			0	70	°C

 All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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SN74ALVCHG162282 **18-BIT TO 36-BIT REGISTERED BUS EXCHANGER** WITH 3-STATE OUTPUTS

SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾	MAX	UNIT
		I _{OH} = -100 μA	3 V to 3.6 V	V _{CC} - 0.2		
V _{OH}	A to B	I _{OH} = -8 mA	3 V	2		V
	B to A	I _{OH} = -6 mA	3 V	2		
		I _{OL} = 100 μA	3 V to 3.6 V		0.2	
V _{OL}	A to B	I _{OL} = 8 mA	3 V		0.8	V
	B to A	$I_{OL} = 6 \text{ mA}$	3 V		0.8	
I _I		$V_{I} = V_{CC} \text{ or } GND$	3.6 V		±5	μA
		V ₁ = 0.8 V	3 V	75		
I _{I(hold)}		V ₁ = 2 V	3 V	-75		μA
		$V_{I} = 0$ to 3.6 $V^{(2)}$	3.6 V		±500	
$I_{OZ}^{(3)}$		$V_0 = V_{CC}$ or GND	3.6 V		±10	μA
I _{CC}		$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	3.6 V		40	μA
ΔI_{CC}		One input at V_{CC} - 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V		750	μA
Ci	Control inputs	$V_{I} = V_{CC}$ or GND	3.3 V	4		pF
Cio	A or B ports	$V_0 = V_{CC}$ or GND	3.3 V	8.5		pF

(1)

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2)another.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC} = ± 0.3	3.3 V 3 V	UNIT
			MIN	MAX	
f _{clock}	Clock frequency			160	MHz
tw	Pulse duration, CLK high or low		2.3		ns
	A data before CLK1	A data before CLK [↑]	1.5		
	Catura time, high an law	B data before CLK↑	2		
t _{su}	Setup time, high or low	DIR before CLK↑	2		ns
		SEL before CLK↑	2		
		A data after CLK↑	0.3		
		B data after CLK↑	0.3		
t _h	Hold time, high or low	DIR after CLK↑	0.3		ns
		SEL after CLK↑	0.3		

SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004

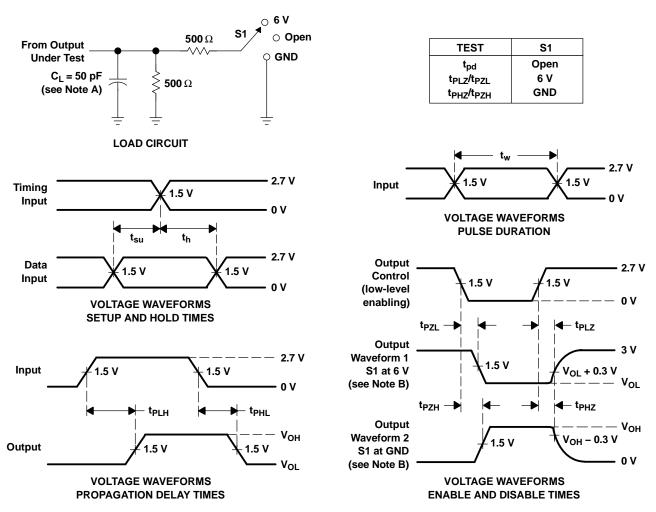


SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 25 \text{ pF}$ (A port), 80 pF (B port) (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INPOT)	(001201)	MIN	MAX	
f _{max}			160		MHz
•	CLK	A	1.5	5	20
t _{pd}	CLK	В	1.5	7.4	ns
	CLK	A	1.5	6.3	ns
		В	1.5	9.4	
t _{en}	ŌĒ	A	1.5	6	
		В	1.5	9.5	
	CLK	A	1.5	6.4	
t _{dis}		В	1.5	7.8	20
	ŌĒ	A	1.5	5	ns
	0E	В	1.5	7.6	

SCES094D-FEBRUARY 1997-REVISED OCTOBER 2004



PARAMETER MEASUREMENT INFORMATION

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

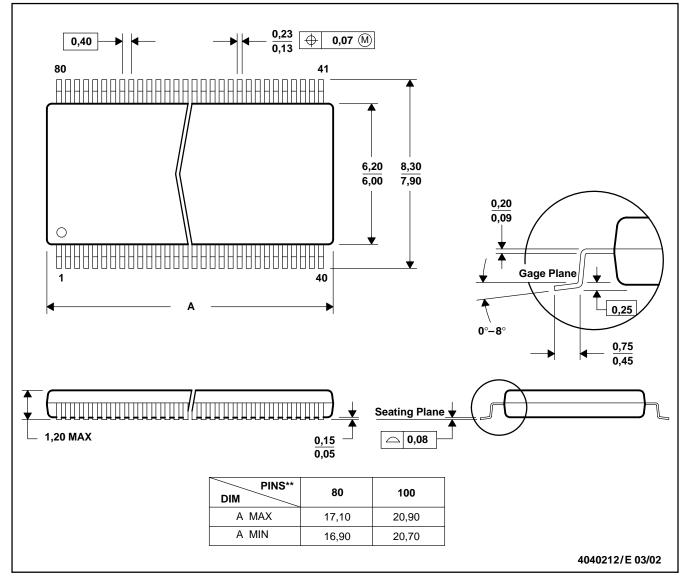
MECHANICAL DATA

MTSS005D - JANUARY 1995 - REVISED MARCH 2002

DBB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

80 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC : 80 Pin – MO-153 Variation FF

100 Pin – MO-194 Variation BB



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